



Continuous innovation and improvement
All employees pursue excellence

Investor Conference

Stock Code : 6207

2025/12/23

LASER TEK TAIWAN CO., LTD.

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Company Overview

Date of Establishment: Sep. 9th, 1988

Capital: 796 Million NT Dollars

President: Tsai-Hsin, Cheng

Employees: Over 300 employees

Worldwide

Prolaser
(KunShan
, China)



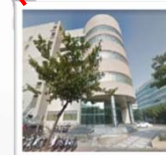
(DongG
uan)



HsinChu Branch



LaserTek Headquarter



Kaohsiung
Hsin Sheng
Building

Laser Tek
(Singapore)



2025 3Q Operating Performance



CONSOLIDATED STATEMENTS OF COMPREHENSIVE INCOME

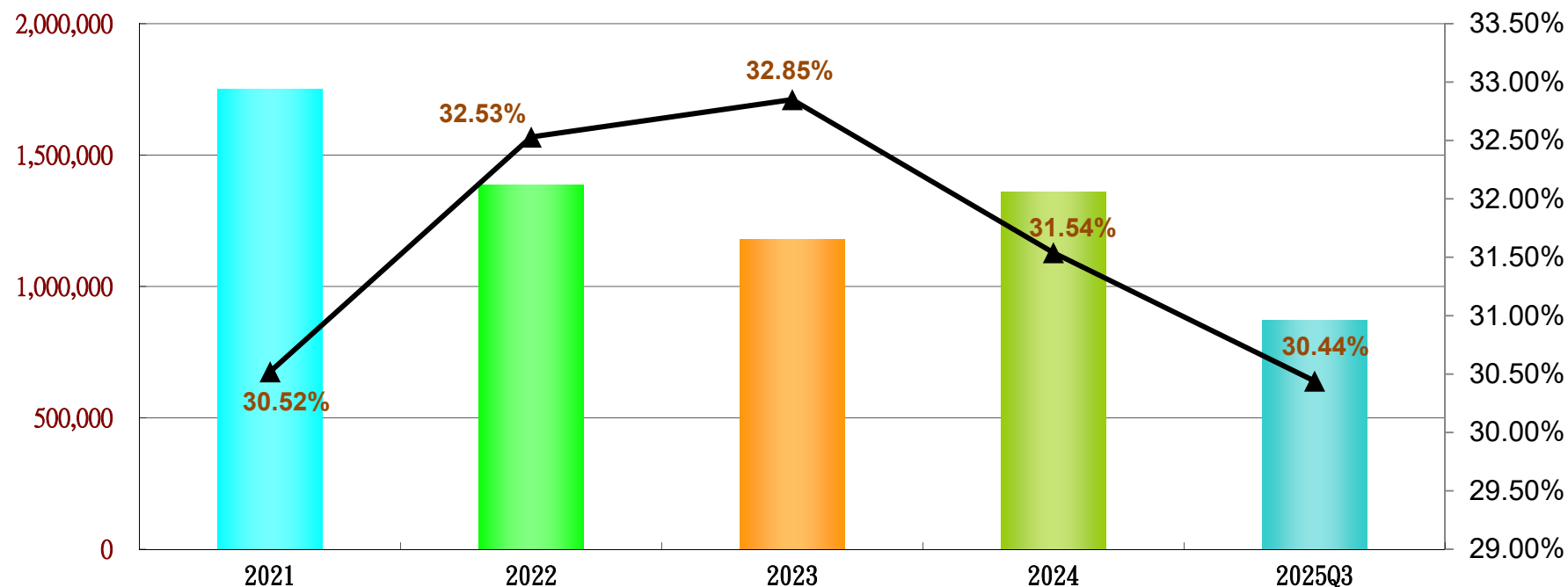
Units : NT\$ Thousand;%

Items	2025 3Q	2024 3Q	2025/3Q Over 2024/3Q
Operating Revenue	872,294	935,808	-6.79%
Gross Margin	30.44%	32.22%	-5.52%
Operating Expenses	216,994	239,291	-9.32%
Operating Margin(Loss)	48,500	62,262	-22.10%
Operating profit margin	5.56%	6.65%	-16.39%
Non-Operating items	21,244	90,656	-76.57%
Net income(Loss) to Shareholders of the Parent	55,759	127,891	-56.40%
Net profit margin	6.39%	13.62%	-53.08%
EPS(NT Dollar)	0.7	1.61	-56.52%



Operating revenue / Gross margin

Units : NT\$ Thousand;%



Items	2021	2022	2023	2024	2025Q3
Revenue	1,751,466	1,386,770	1,177,816	1,361,184	872,294
Gross Margin	30.52%	32.53%	32.85%	31.54%	30.44%

Products And Technologies



Product Business Group

60%



設備事業 (Laser & Metrology Equipments)

LASER Equipment

COWOS Equipment

40%



SMD捲裝材料事業 (Surface Mount Device Packaging Materials)

Passive components
Packaging Materials

Semiconductor components
Packaging Materials



Energy Saving Devices / GERMAGIC防疫產品

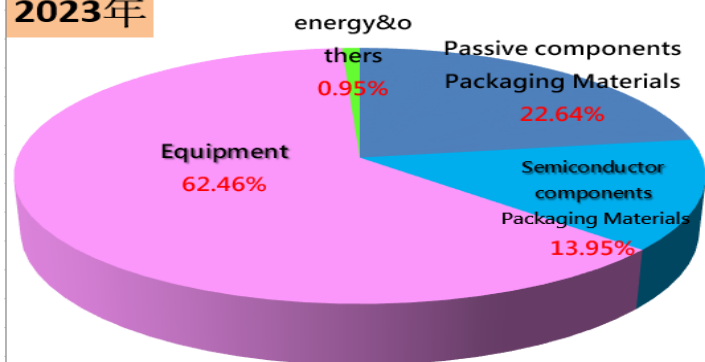
Solar energy related
businesses

Air Purifier

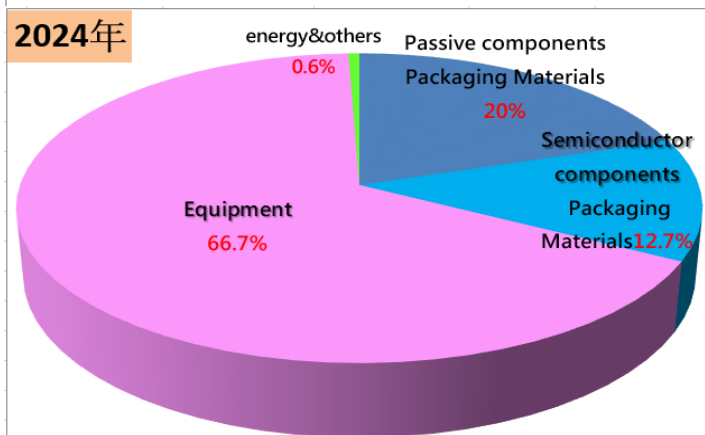
GERMAGIC Epidemic
Prevention Products

Products revenue share %

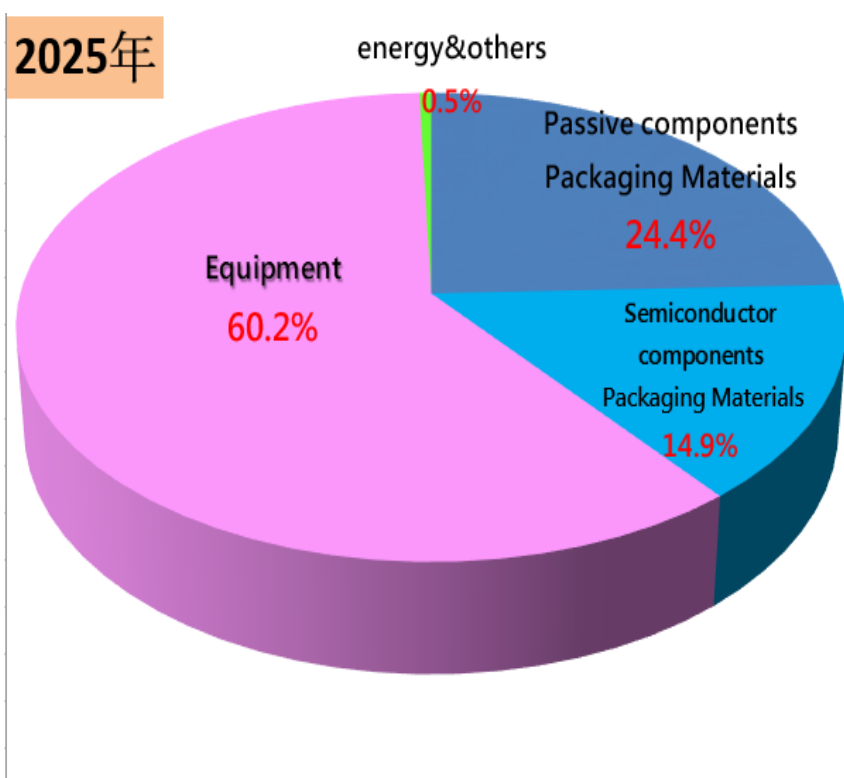
2023年



2024年



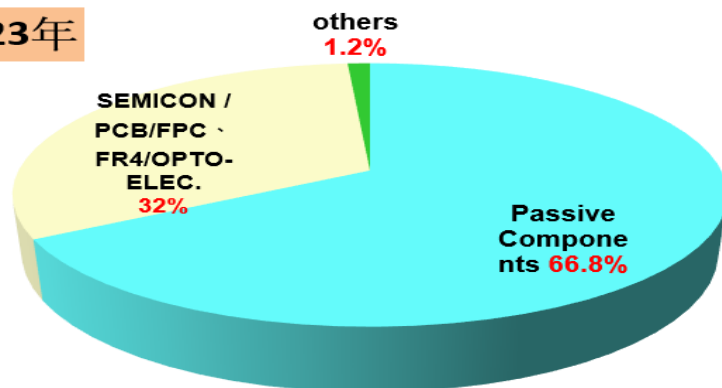
2025年



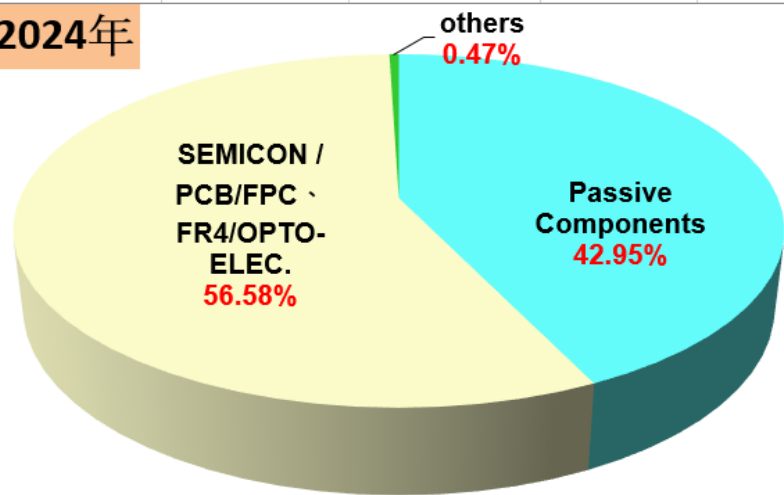
追求卓越

Industry revenue percentage of products

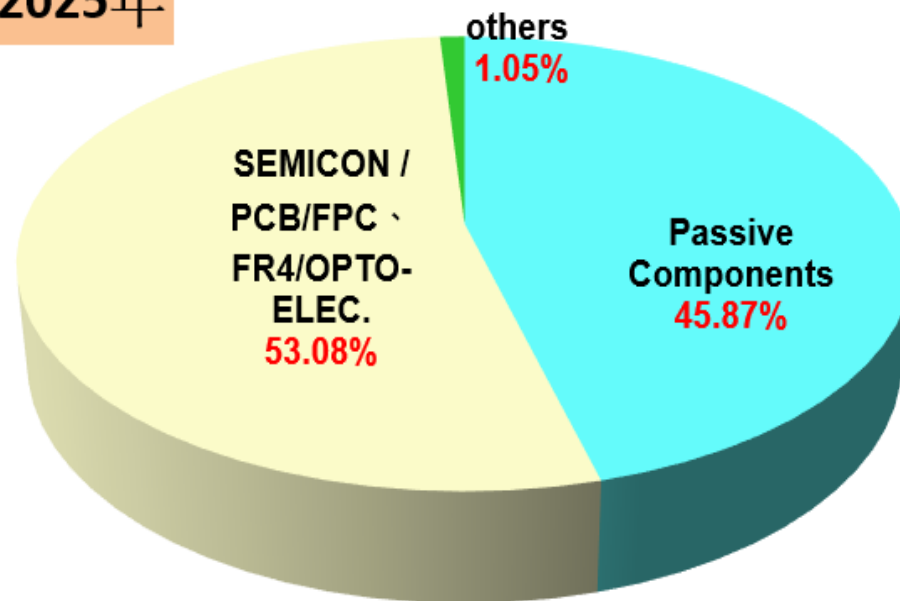
2023年



2024年



2025年

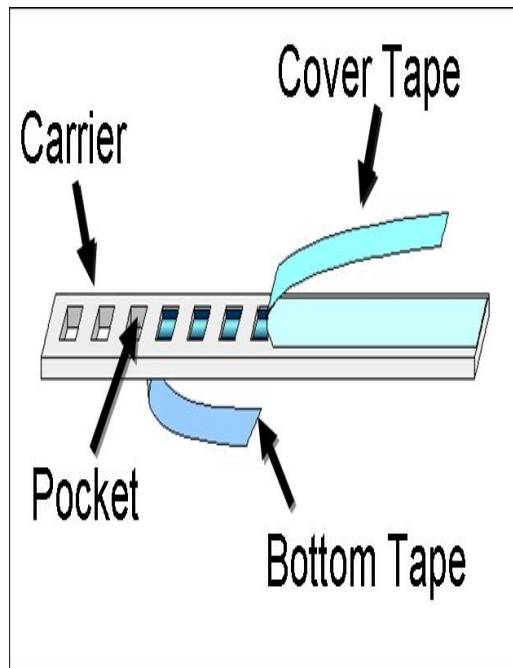


市場 · 提供完整服務方案



➤ Surface Mount Device Packaging Materials

Passive components Packaging Materials



**Slitting
Carrier Tape**

Composed of 7 layers of
pulp



**Punched
Carrier Tape**

Specialized cavity
development to meet
various size requirements



Cover Tape

Excellent antistatic effect



Bottom Tape

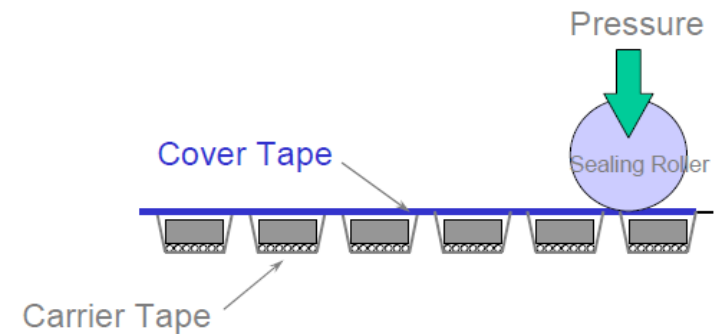
Made of rice paper, coated
with sealant and
polyethylene, antistatic.



➤ Surface Mount Device Packaging Materials

Semiconductor components Packaging Materials

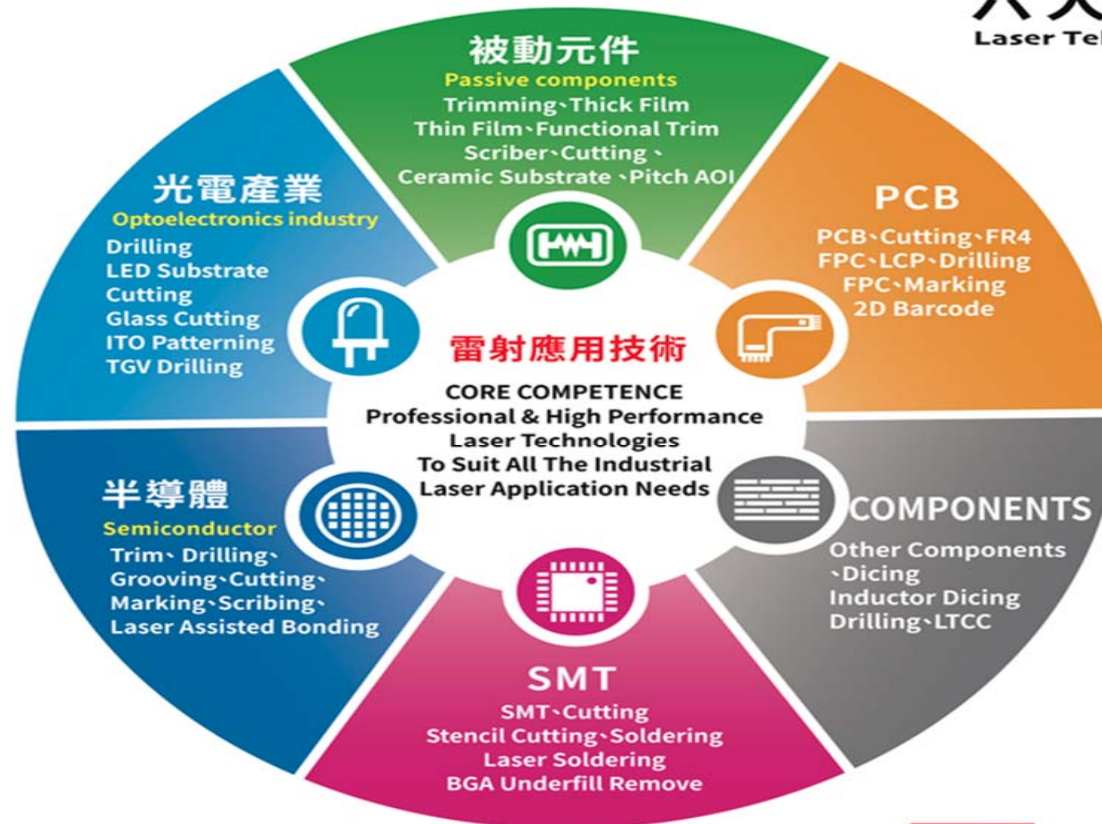
- Carrier Tape : Packaging tapes for IC semiconductors, electronic passive components, LED products, etc.
- The main materials are PC, PS... and other plastic raw materials.



Laser Core Competitiveness & Territory

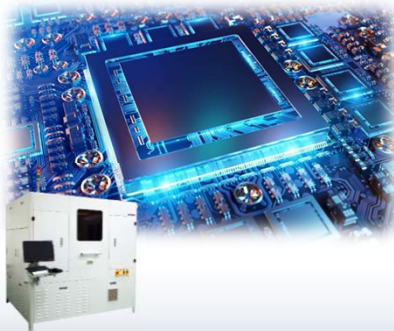
六大核心技術

Laser Tek Core Technologies



➤ Four Core Laser Technology

Semiconductors



- Wafer Trimming
- CoWoS Inspection
- TSV (Through-Silicon Via)
- SiC Cutting
- TGV (Through-Glass Via)
- OSAT Assembly

Substrates



- FR4 Automotive Electronics
- Drilling and Cutting of AlN Substrates
- AI Computing Substrates
- Laser Dry Etching
- ABF Drilling for Servers

Components



- Thick Film
- Thin Film (High Precision)
- Functional Trimming
- Socket Base Cutting

AI Applications

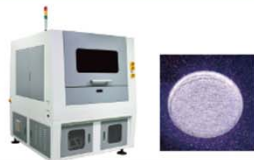


- AI Defect Inspection
- AI Diamond Cutting
- AI GPU Adhesive Removal

Semiconductor Field

Laser Equipment--- Front-end cutting & drilling/ Mid-end Test / Back-end Package

晶圓製造 Wafer Manufacture



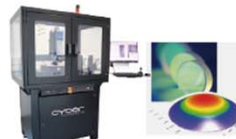
TSV 飛秒鑽孔機 TSV Femto Drilling

特殊光學套件，進行矽晶圓穿孔與盲孔冷加工
Special Optical Modules for Cold Processing of Silicon Wafers with Through-Holes and Blind Holes.



SiC 飛秒切割機 SiC Femto Cutting

特殊光學套件，進行SiC削蝕冷加工切割
Special Optical Modules for SiC Etching and Cold Laser Cutting Process.



Cyber 設備 Cyber Equipment

高階2D/3D非接觸式雷射掃描設備
High-end 2D/3D Non-contact Laser Scanning Equipment.

中段測試 Mid-stage Testing



Wafer Trim

透過光學鏡組，進行對SiC削蝕
Etching of SiC Through Optical Lens.



Functional Trim

混成電路IC功能修調，高精度量測，精密修調
Hybrid Circuit IC Function Trimming, High-Precision Measurement, and Trimming.

後段封裝 Back-end Process



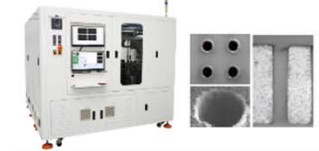
FR4 & ABF Laser Drilling and Cutting

封裝基板層間導通孔 (Via Hole)
ABF 層微孔鑽孔 Substrate 外形切割/分板
多層結構材料精密開窗與去除



Wafer Marking

IC Marking, Wafer Marking.



RF High Frequency Substrate

高頻RF散熱基板 - 低軌衛星 (LEO) 應用



Laser Deflash

Lead frame 修整去毛邊
四點對位漲縮補償
Lead Frame Deburring,
Four-Point Alignment with Expansion
and Contraction Compensation.



FOPLP

玻璃基板去除膠體
Glass Substrate Adhesive Removal.



Cyber 設備 Cyber Equipment

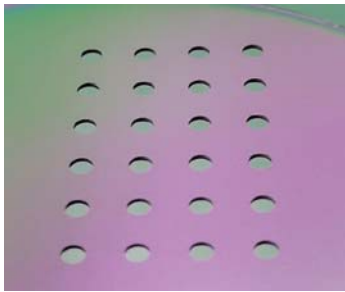
高階2D/3D非接觸式雷射掃描設備
High-end 2D/3D Non-contact Laser Scanning Equipment.



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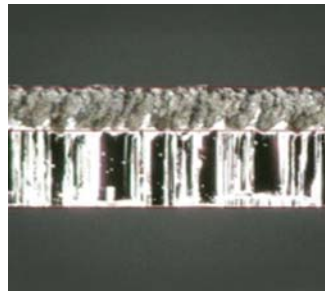
Semiconductor Field

Front-end cutting & drilling/Wafer Manufacture



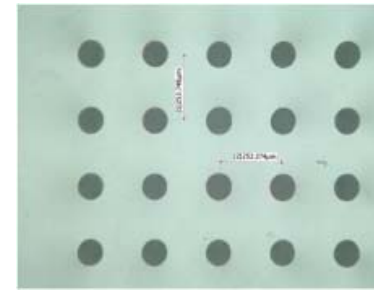
TSV Femto Drilling

TSV飛秒鑽孔機 - 特殊光學套件
進行矽晶圓穿孔與盲孔冷加工



SiC Femto Cutting

SiC飛秒切割機 - 特殊光學套件
進行SiC削蝕冷加工切割



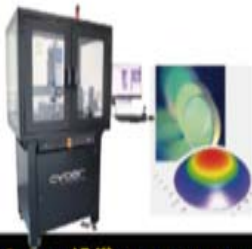
TGV Femto Drilling

超快雷射技術可達每秒數千孔，
大幅提高生產速度，滿足大批量需求



Semiconductor Field

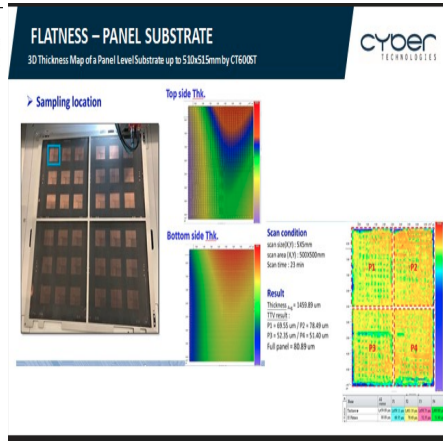
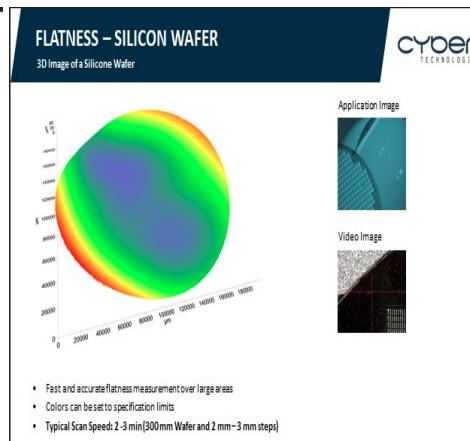
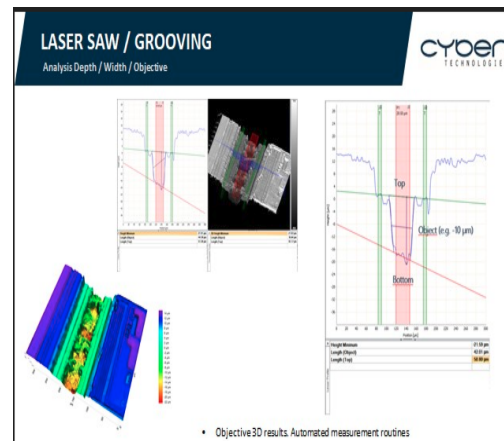
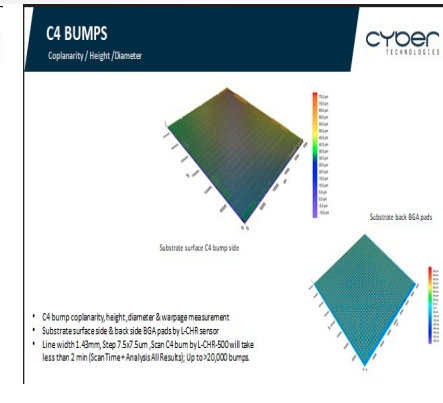
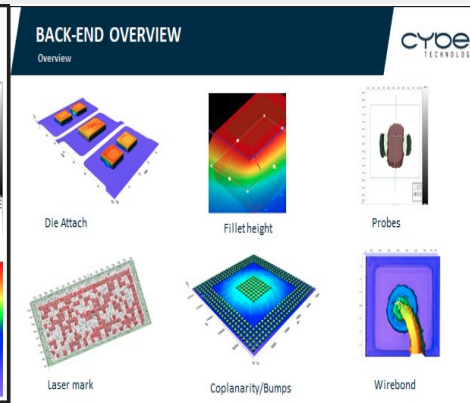
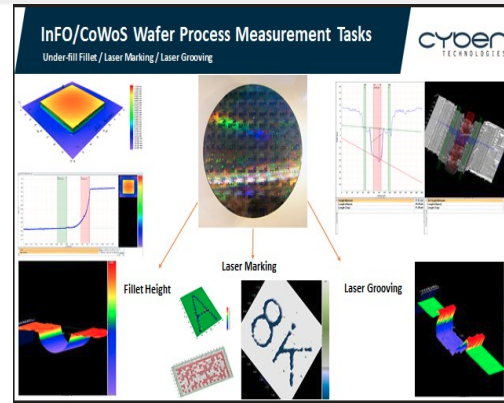
Front-end Wafer Manufacture / Back-end Package



Cyber 設備 Cyber Equipment

高階2D/3D非接觸式雷射掃描設備

High-end 2D/3D Non-contact Laser Scanning Equipment.

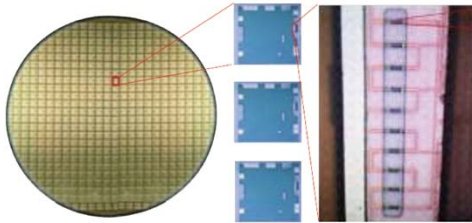


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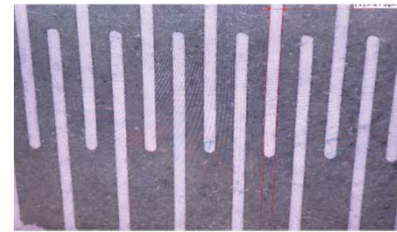
Semiconductor Field

Laser Equipment--- Mid-end Test



Wafer Trim

Semiconductor wafer trimming, Online real-time measurement and trimming



Functional Trim

Hybrid IC Function Adjustment:
High-precision measurement and fine-tuning.



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Semiconductor Field

Back-end Package



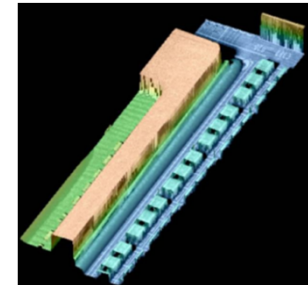
Wafer Marking

Hard and soft marking can quickly complete wafer marking, suitable for large-scale production lines.



Laser Deflash

Lead frame trimming and burr removal; four-point alignment and expansion/contraction compensation.



FOPLP

Glass substrate adhesive removal: high precision, non-contact, non-destructive, and highly efficient, accurately removing residual adhesive.

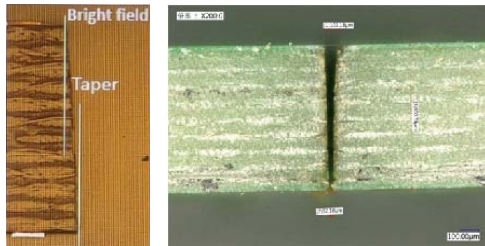


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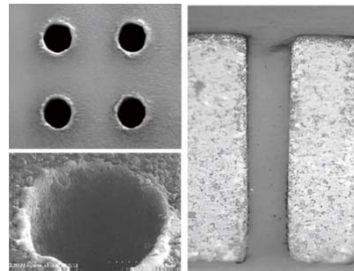
Substrate Application

Laser application equipment --- Advanced semiconductor packaging substrates / RFPCB



FR4 & ABF Laser cutting & laser thick core drilling

Multilayer vias (Via Holes) in packaging substrates
 ABF layer micro-hole drilling
 Substrate cutting/separation
 Precision windowing and removal of multilayer structural materials



High-frequency RF heat dissipation substrate LEO application



High precision Rigid-flex PCB cutting Consumer electronic board

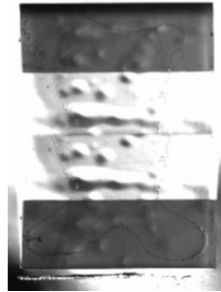


➤ AI Application

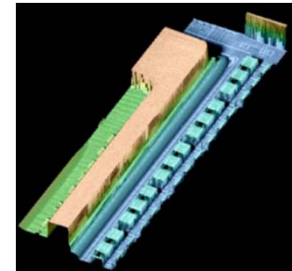
Laser application equipment --
AI+AOI+Laser



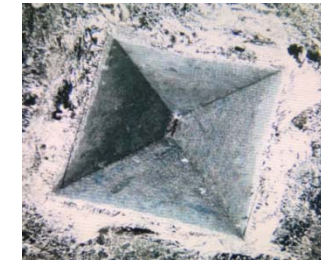
AI defect inspection
Laser Applications in Various Components



AI Transparent contour construction
VR/AR glass cutting application



AI-generated colloid height profile
AI chip adhesive removal application



AI Image Recognition
Laser application on reflective materials





持續創新改善 全員追求卓越

感謝您的蒞臨

Thank you for coming here today.

LASER TEK TAIWAN CO., LTD.